MATERIAL DECLARATION SHEET

BOURNS®

Package Type	TBU-CA Series				
Product Line	Semiconductor Products				
Compliance Date	January 1, 2010				
RoHS Compliant	Yes	Terminal	e3	MSL	1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.032629	Silica fused	60676-86-0	90.450	37.429	41.38
				Epoxy Resin	Trade Secret	6.000	2.482	
				Phenol Resin	Trade Secret	3.000	1.241	
				Carbon Black	1333-86-4	0.550	0.228	
2	Leadframe	Copper alloy	0.037765	Copper	7440-50-8	97.585	46.7415	47.90
				Iron	7439-89-6	2.236	1.072	
				Phosphorus	7723-14-0	0.076	0.037	
				Zinc	7440-66-6	0.102	0.049	
				Lead (impurity)	7439-92-1	0.001	0.0005	
		Silver Plating	0.000623	Silver	7440-22-4	100.000	0.790	0.79
3	Chip	Silicon	0.003941	Silicon	7440-21-3	100.000	5.000	5.00
4.	Die Attach	Silver Epoxy	0.001296	Silver	7440-22-4	93.400	1.53176	1.64
				Epoxy resin	Trade Secret	5.500	0.0902	
				Polymeric compound	Trade Secret	1.100	0.01804	
5	Bond Wires	Gold	0.000188	Gold	7440-57-5	99.990	0.23976	0.24
				Non-Au elements	Trade Secret	0.010	0.00024	
6	Lead Finish	Matte Tin	0.002407	Tin	7440-31-5	100.000	3.050	3.05
		Total Weight	0.078849					

Important remarks:

1. It is responsibility of the user to verify they are accessing the latest version.

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society